AMENDMENTS TO THE CLAIMS

1-20. (Cancelled).

21. (New) A device for maintaining a microprocessor in a desired relationship with a printed wiring board, comprising:

a plurality of interposer columns connecting the microprocessor to the printed wiring board and allowing relative motion between the microprocessor and the printed wiring board; and

an isolating mount compressed between the microprocessor and the printed wiring board;

wherein said isolating mount is adapted to dampen vibrational motion transmitted by said interposer columns between the printed wiring board and the microprocessor.

22. (New) The device of claim 21 wherein said plurality of interposer columns possess a total spring constant and said isolating mount possesses a damping value.

23. (New) The device of claim 21 wherein said isolating mount comprises a continuous piece of material that contacts the periphery of the microprocessor.

24. (New) The device of claim 21 wherein said isolating mount comprises a plurality of pieces of material that contact the microprocessor.

25. (New) The device of claim 21 wherein said isolating mount comprises material resistant to temperatures below 130°C.

26. (New) The device of claim 21 wherein the isolating mount possesses a loss factor of at least 0.010.

27. (New) The device of claim 21 further comprising a heat sink connected to the microprocessor and the printed wiring board by an assembly comprising at least one spring.

28. (New) The device of claim 21 wherein said plurality of interposer columns and said isolating mount are arranged in series.

29. (New) The device of claim 21 wherein said plurality of interposer columns and said isolating mount are arranged in parallel.

30. (New) The device of claim 21 further comprising:

a chassis supporting the printed wiring board; and

an input device connected to the printed wiring board.

31. (New) A device for minimizing the vibrational motion in a microprocessor connected to a printed wiring board, the device comprising:

means for connecting the microprocessor to the printed wiring board that electrically connects the microprocessor to the printed wiring board, wherein said means for connecting transmits vibrational motion and allows relative motion between the microprocessor and the printed wiring board; and

means for damping vibrational motion transmitted between the microprocessor and the printed wiring board.

32. (New) The device of claim 31 wherein said means for connecting has a spring constant and said means for damping has a damping value.

33. (New) The device of claim 31 wherein said means for connecting and said means for damping comprise a Kelvin system.

34. (New) The device of claim 31 wherein said means for connecting and said means for damping comprise a Maxwell system.

35. (New) The device of claim 31 wherein the device displays a viscoelastic response to applied loads.

36. (New) The device of claim 31 further comprising a heat sink connected to the microprocessor and the printed wiring board by an assembly comprising at least one spring.

37. (New) The device of claim 31 further comprising:

a chassis supporting the printed wiring board; and

an input device connected to the printed wiring board.

38. (New) A method for mounting a microprocessor to a printed wiring board, the method comprising:

connecting a plurality of interposer columns between the printed wiring board and the microprocessor such that the microprocessor can move relative to the printed wiring board and vibrational energy is transferred between the printed wiring board and the microprocessor through the interposer columns; and

compressing an isolating mount between the printed wiring board and the microprocessor such that the isolating mount dampens the vibrational energy transferred through the interposer columns.

39. (New) The method of claim 38 wherein the plurality of interposer columns possess a total spring constant and the isolating mount possesses a damping value.

40. (New) The method of claim 38 wherein the isolating mount comprises a continuous piece of material that is compressed against the periphery of the microprocessor.

41. (New) The method of claim 38 wherein said isolating mount comprises a plurality of pieces of material.

42. (New) The method of claim 38 wherein the isolating mount comprises material resistant to temperatures below 130°C.

43. (New) The method of claim 38 wherein the isolating mount possesses a loss factor of at least 0.010.

44. (New) The method of claim 38 wherein the plurality of interposer columns and the isolating mount are arranged in series.

45. (New) The method of claim 38 wherein the plurality of interposer columns and the isolating mount are arranged in parallel.